



SPECIFICATIONS:

- ELECTRICAL CHARACTERISTICS:
 - RATING: 12V 1A
 - CONTACT RESISTANCE: 30mΩ MAX.(INITIAL)
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC
- MECHANICAL CHARACTERISTICS:
 - INSERTION FORCE : 0.3~3.0 KGf
 - WITHDRAWAL FORCE : 0.3~3.0 KGf
 - LIFE TEST: 5,000 CYCLES MIN.
 - OTHER GENERAL SPEC. TO REFER "2SU2271 SPEC".
 - TO CONFORM TO THE SINGATRON HSF SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.
 - SOLDER HEAT RESISTANCE REFLOW SOLDERING 260°C 10SECS.
 - DATE CODE:YY MM DD



RECOMMENDED PCB LAYOUT
TOP VIEW (TOLERANCE:±0.05)

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
E	BODY	1	THERMOPLASTIC HIGH TEMP	BLACK COLOR
D	RING SPRING A	1	COPPER ALLOY 0.2t	GOLD FLASH
C	TIP SPRING	1	COPPER ALLOY 0.2t	GOLD FLASH
B	RING SPRING B	2	COPPER ALLOY 0.2t	GOLD FLASH
A	EARTH	1	COPPER ALLOY 0.2t	GOLD FLASH

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:

X : ±0.5 X : ±2°
 X.X : ±0.3 X.X : ±1°
 X.XX : ±0.2

TITLE	3.5mm PHONE JACK
DWN	KIM PART NO. 2SU2271-002121
CHKD	TOW SCALE 6:1 UNIT: mm
APVD	SEN SIZE: A3 SHEET: 10F1 REV: A

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信亨企業股份有限公司

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REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	Kim	2011.03.30